

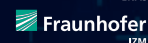
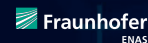
smartsystems integration

International Conference and Exhibition
on Integration Issues of Miniaturized Systems

Call for Papers

Barcelona, Spain, 10 – 11 April 2019
smartsystemsintegration.com

Co-organizer:



mesago
Messe Frankfurt Group

Invitation SSI 2019

Currently, digitization is entering all sectors. Traditional sectors merge with digital solutions and our world is becoming more and more connected. Thereby, big challenges arise in the field of less power consuming and multifunctional hardware as well as on data security, responsible handling of data and constantly updated legal regulations. The main hardware components of the IoT are smart systems – self-sufficient, mostly autonomous intelligent technical systems with advanced functionality. Their operation is being further enhanced by their ability to mutually address, identify and work in consortia with each other. Therefore, smart systems hold not only enormous potential for a wide range of applications, they also act as enablers for many future technologies.

The ecosystem of smart systems in Europe is mainly driven by EPoSS – the European Platform on Smart Systems Integration. The objectives of EPoSS consist of further developing the European industry network for the promotion of research in Smart Systems technologies, defining R&D priorities and policy requirements, co-ordinating efforts, launching common actions, and implementing joint R&D strategies. In this sense, the Smart Systems Integration Conference and Exhibition is the most important platform for industry, science and politics to exchange know-how and knowledge as well as initiate new projects in this field.

The Smart Systems Integration Conference 2019 addresses all aspects of smart systems, starting from new materials and technologies, issues of integration, innovative smart systems, their manufacturing technologies, embedded software up to industrial applications.

On behalf of the committee, the Co-Chairs – Dr. Stefan Finkbeiner (Bosch Sensortec GmbH, Chairman of EPoSS) and Wolfgang Gessner (EPoSS Office) – and the local Co-Chairs from Spain – Prof. Carles Cané (CNM-IMB), Dr. Larraitz Añorga (CIDETEC), Dr. Chris Merveille (IKERLAN) and Dr. Luis Fonseca (CNM-IMB) – I am looking forward to receiving your application or scientific oriented submission.



Prof. Dr. T. Otto
Fraunhofer Institute for Electronic Nano Systems
Conference Chair Smart Systems Integration 2019

Conference topics 2019

A. Applications

- A01 Smart mobility
- A02 Smart health and wellness
- A03 Smart energy
- A04 Smart society
- A05 Smart production

B. Hardware/Technologies

- B01 New materials for nano structures and devices
- B02 Design of smart integrated systems
- B03 Advanced micro and nano technologies
- B04 Smart low cost approaches including Roll-to-Roll technologies and printed functionalities
- B05 System integration: 3D integration, interconnect technologies and packaging
- B06 Smart test and reliability of components and systems
- B07 Manufacturing of embedded micro and nano systems

C. Software for smart integrated systems

- C01 Embedded software
- C02 Distributed embedded systems
- C03 Self-X systems (learning, organising, optimising, repairing ...)
- C04 Methods of software life cycle (design, test, commissioning ...)

D. Business creation of Smart Systems

- D01 Market Trends
- D02 Perspectives of Smart Systems
- D03 Ecosystems for Smart Solutions
- D04 SME success stories

Online submission until 10 October 2018
at smartsystemsintegration.com/callforpapers

Become a speaker!

Highlight your expertise at the SSI
conference with concurrent exhibition!

Your advantages

- Present your knowledge to a highly qualified audience.
- Exchange your experience with other international experts from all over Europe.
- Enjoy the conference dinner with colleagues and network with business partners in a special atmosphere.
- Publish your paper in the Smart Systems Integration proceedings with ISBN.
- Publish your presentation in the online and printed conference program.
- Benefit from maximum attention for your presentation due to extensive press work and advertising activities.
- Take the opportunity to win the Best Paper or Best Poster Award.
- Invite your colleagues and business partners at special conference prices.

The conference committee decides on the acceptance of submissions.



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Submission requirements

Conference language

English

Conditions of acceptance

Authors are expected to secure the registration fee of 335 EUR + VAT as well as travel and accommodation funding through their sponsoring organizations, before submitting abstracts. Full payment will be due once the submission has been accepted. Only original material should be submitted. Government and company clearance to present and publish should be finalized at the time of submission. Non-research based papers which attempt to promote commercial products cannot be submitted.

Selection process

The committee will review all submitted abstracts to maintain the high quality of the conference. Only papers submitted on time and addressing subjects which are topical and relevant to the conference will be considered for inclusion in the conference programme. Submitted papers may be selected for oral or poster presentations.

Oral and poster presentations

Oral presentations will be held in different sessions. The duration of each presentation should not exceed 25 minutes including 5 minutes for subsequent discussions. Poster authors will have the opportunity to present their posters during a special poster session and throughout the conference. All oral and poster presentations will be included in the conference proceedings.

Deadlines

Submission of abstracts

10 October 2018

Selection by committee

5 November 2018

Submission of full manuscripts

28 February 2019

Submission no later than 10 October 2018
at smartsystemintegration.com/callforpapers

» **One has a comprehensive view of what is currently happening in the microelectronics industry – all under one roof and from a single source. Everyone involved in the field gathers at one place: from individual companies, research institutes and research funders as well as a diverse range of non-university institutes.** «

Georg Weigelt, PR & Marketing, Fraunhofer Institute for Reliability and Microintegration IZM

Impressions of SSI 2018 | Exhibition and conference in Dresden, Germany

